

HIGH DENSITY INTERNAL BALL GRID ARRAY  
INTEGRATED CIRCUIT PACKAGE

09/11/5444

ABSTRACT OF THE DISCLOSURE

5 An integrated circuit package (30) comprising a substrate  
(70) having peripheral openings (86) and first and second  
surfaces (92, 94), a plurality of routing strips (82) being  
integral with the substrate (70), a plurality of pads (100)  
centrally disposed on the first surface (92) and electrically  
connected with at least one of the routing strips (82), a chip  
(50) having bonding pads (120) adhered to the second surface  
(84) of the substrate (70), wire bonding (80) electrically  
connecting at least one bonding pad (120) to at least one of  
the routing strips (82) and potting material (90) filling the  
openings (86) to adhere the chip (50) to the substrate (70)  
and surrounding the wire bonding (80), is disclosed.

Y:\FIRM\CLIENTS\TI - 1410\2104\high density BOC module.wpd